/ Descriptions

SOT23-6 P MOS

P- CHANNEL MOSFET in a SOT23-6 Plastic Package.

/ Features

V_{DS} (V) = -12V I_D = -8.0A

$R_{DS(ON)}$@-10V≤20mΩ(Type.18mΩ)

$R_{DS(ON)}$@-4.5V≤25mΩ(Type.21mΩ)

$R_{DS(ON)}$@-2.5V≤30mΩ(Type.27mΩ)

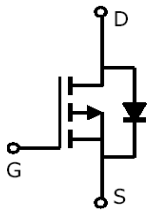
$R_{DS(ON)}$@-1.8V≤50mΩ(Type.40mΩ)

HF Product.

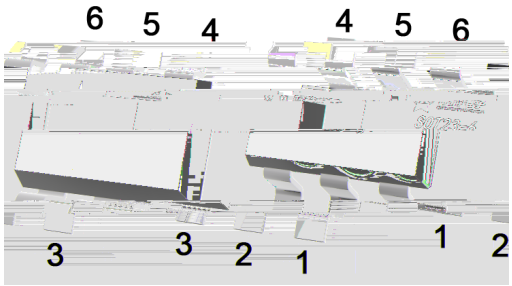
/ Applications

PWM applications,Load switch,Power management.

/ Equivalent Circuit



/ Pinning



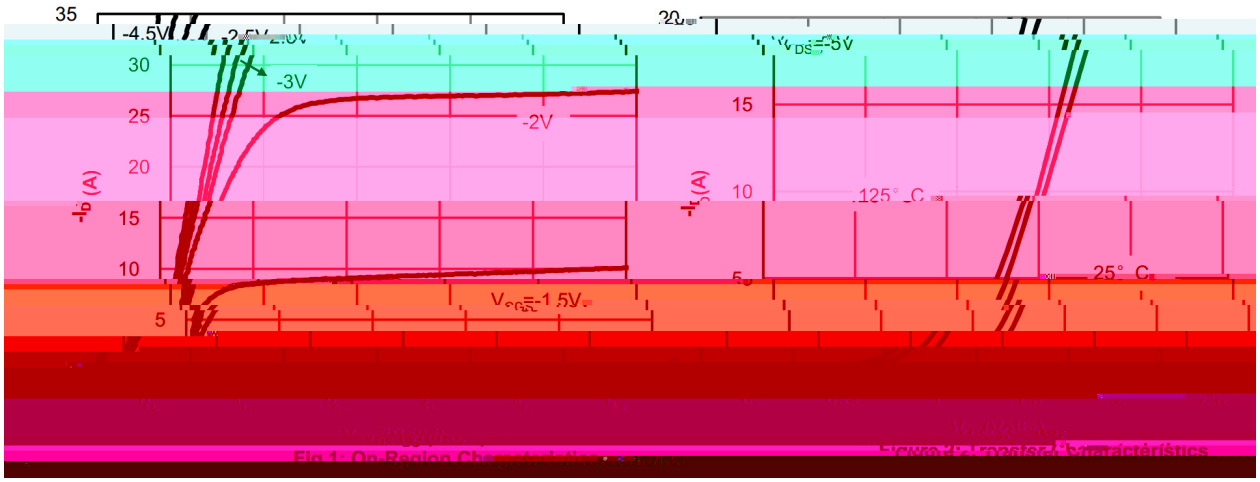
PIN1 2 5 6 D PIN 3 G PIN 4 S

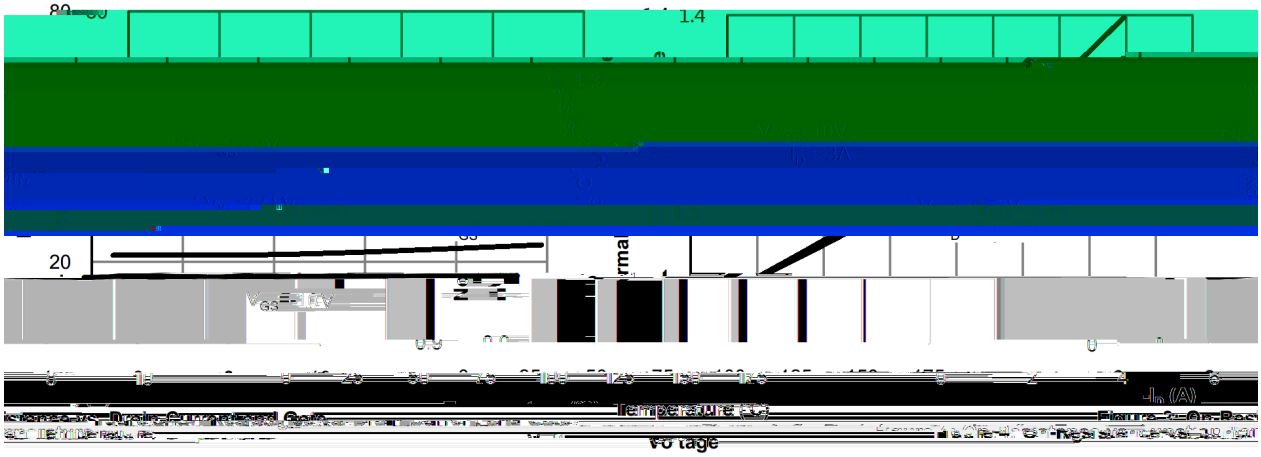
/ Marking

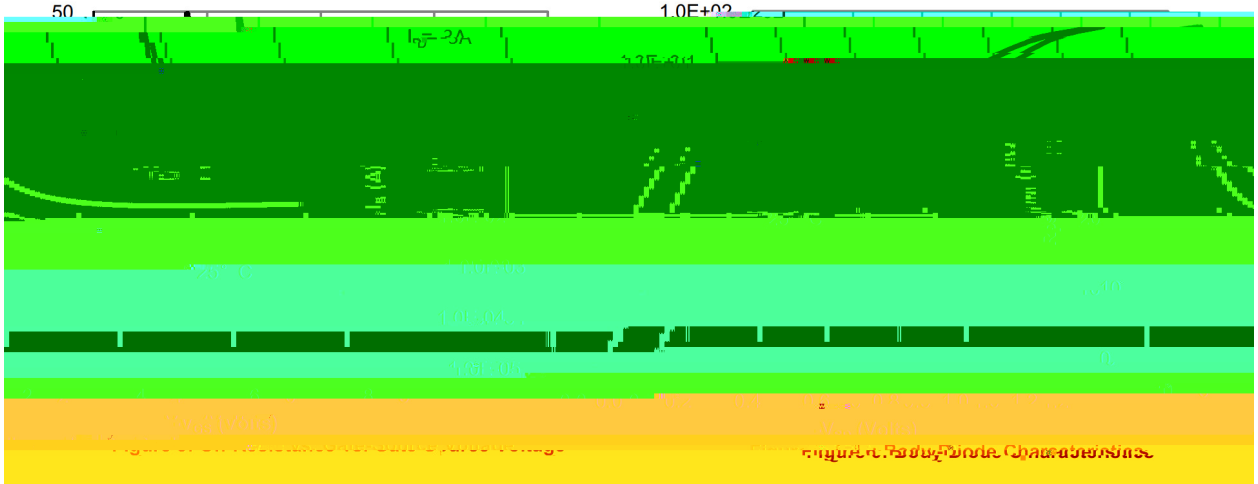
See Marking Instructions.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_g	V_{GS}=-4.5V V_{DS}=-6V I_D=-8A		.974001.45mD60f3.00175		1

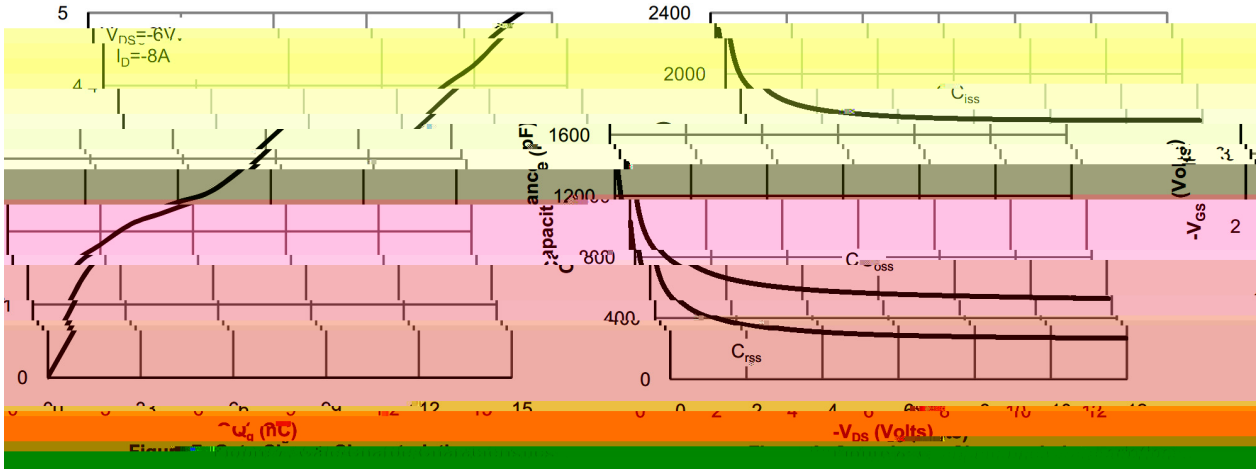
/ Electrical Characteristic Curve







/ Electrical Characteristic Curve



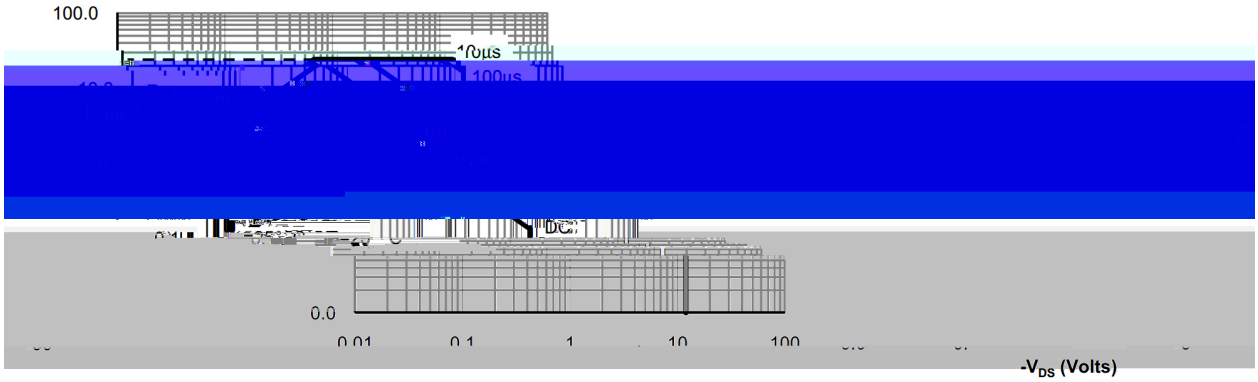
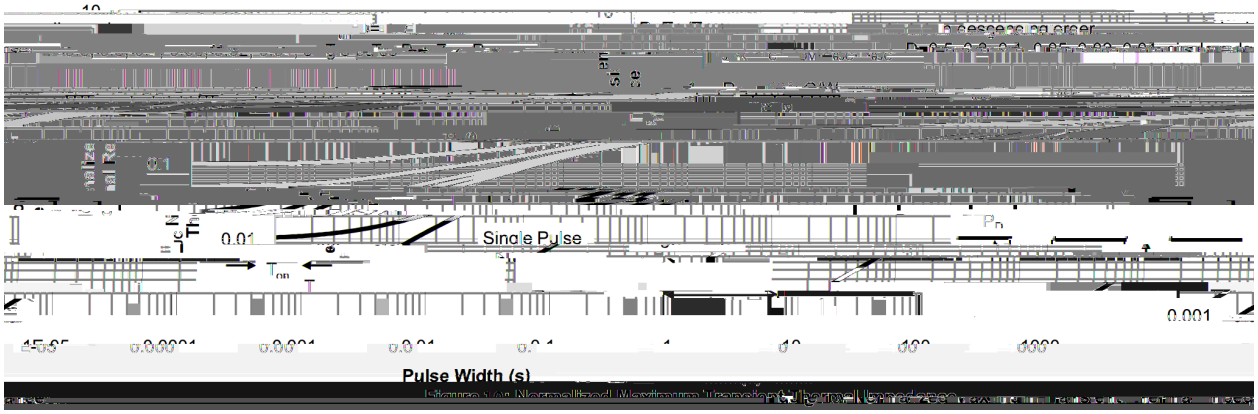
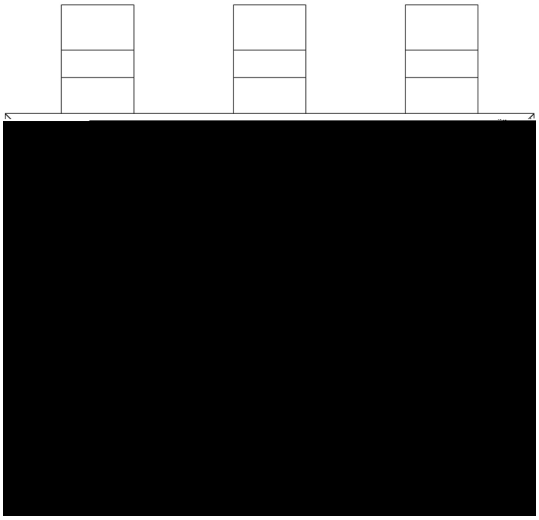


Figure 9: Maximum Forward Biased Safe Operating Area



/ Marking Instructions



C3

H

****

Note:

C3: Product Type Code

H: Company Code

**** Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box